

# Multilayer Ceramic Chip Capacitors

### C0603X6S1A224M030BC



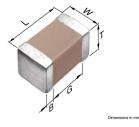






#### TDK item description C0603X6S1A224MT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C0603 [EIA 0201]	
Status	Production (Not Recommended for New Design)	



	Size	
Length(L)	0.60mm ±0.05mm	
Width(W)	0.30mm ±0.05mm	
Thickness(T)	0.30mm ±0.05mm	
Terminal Width(B)	0.10mm Min.	
Terminal Spacing(G)	0.20mm Min.	
Recommended Land Pattern (PA)	0.25mm to 0.35mm	
Recommended Land Pattern (PB)	0.20mm to 0.30mm	
Recommended Land Pattern (PC)	0.25mm to 0.35mm	

Electrical Characteristics		
Capacitance	220nF ±20%	
Rated Voltage	10VDC	
Temperature Characteristic	X6S(±22%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	454ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	15000pcs

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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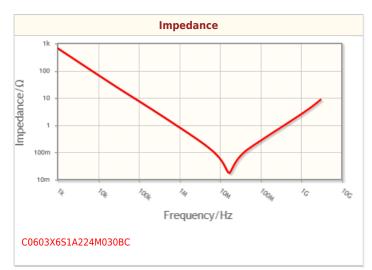


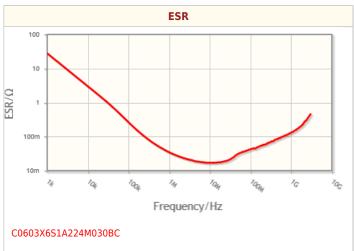


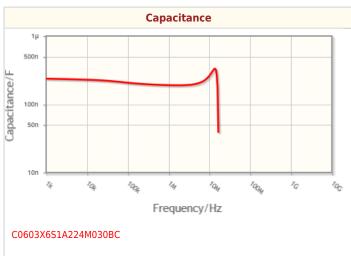


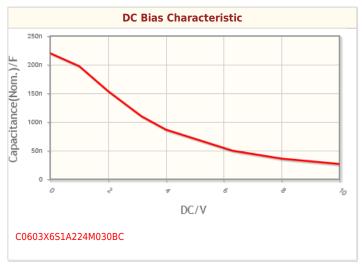


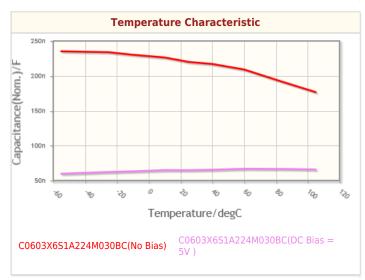
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

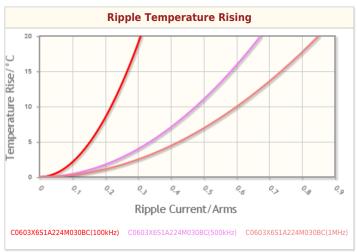












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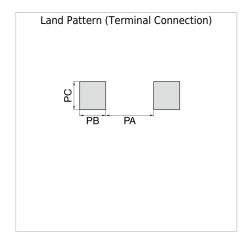








# **Associated Images**



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